

2層FCCLのNi-Cr-Moシード層のエッチング性および耐食性

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Etchability and Corrosion Resistance of Ni-Cr-Mo Seed Layer for Two-Layer FCCL

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Abstract

In this paper, the etchability and corrosion resistance of a Ni-Cr-Mo seed layer for Two-layer FCCL (Flexible Copper Clad Laminate) are evaluated. It is clearly shown that the seed layer coated by sputtering has a high corrosion resistance because the crystal structure is close to amorphous. It is found that the corrosion resistance to chloride ions was enhanced by the addition of Mo to the Ni-Cr seed layer with the Mo content range from 0.5 to 4 mass%. The lower limit is determined by the electrochemical migration resistance, and the higher limit is determined by the etchability.

Key Words: Ni-Cr-Mo Alloy, Seed Layer, Etchability, Corrosion Resistance, FCCL (Flexible Copper Clad Laminate)